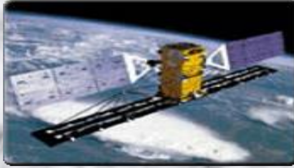
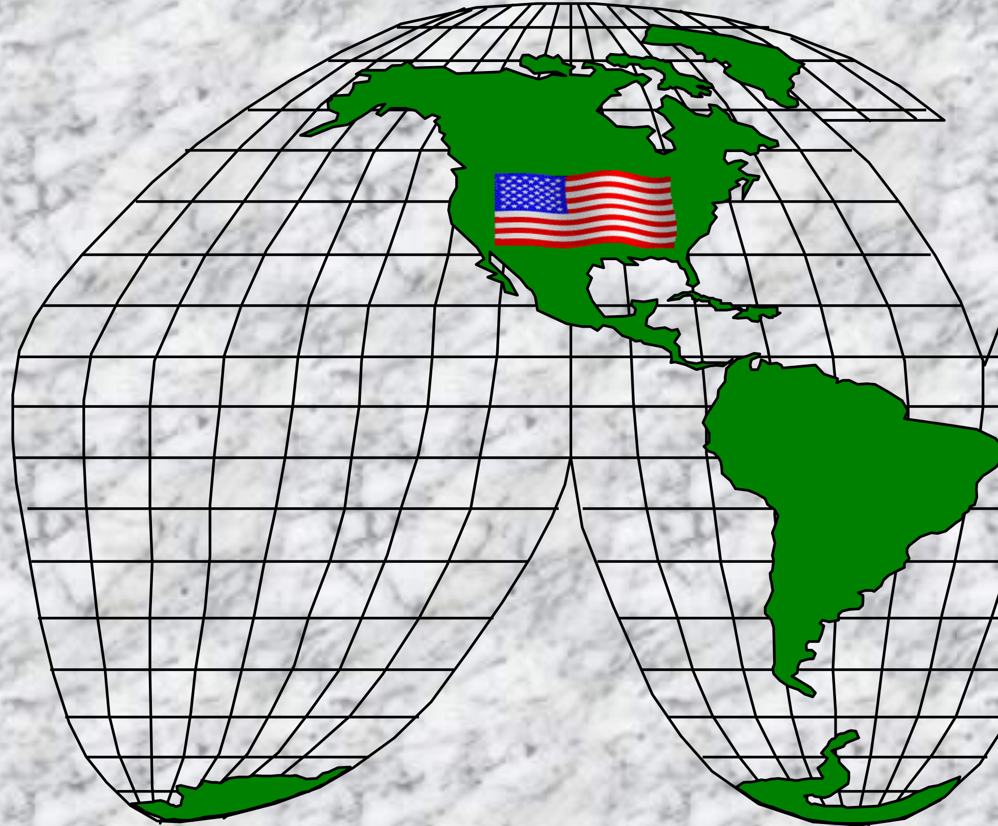
MICROCOAT TECHNOLOGIES





Prosper, Texas, Cheshire, CT, Research Triangle Park, NC USA

http://www.m-coat.com

Introducing MicroCoat's Breakthrough Product: MCT SD0802-31DA – The Ultimate Conductive Die Attach Adhesive

Our game-changing adhesive, MCT SD0802-31DA, offers unmatched performance for your packaging needs.

Extremely low moisture absorption and anti-bleed resin technology for superior wirebond and packaging performance.

Key Features

Moisture Absorption: Passed >1 year at 30°C/85%RH, suitable for MSL1 packaging
Epoxy Ring: <50um spread uncured for 2 hours, <75um spread when cured for 1 hour at 150°C
Application Range: Ideal for Military, Medical, optoelectronics, automotive sensors, and more
Versatile Compatibility: Bonds ICs and components to ceramic, PBGAs, CSPs, LCP, and array packages
Stability: Hydrophobic and stable at high temperatures
Exceptional Bond Strength: Interfacial adhesion to various organic and metal surfaces
Reliability: Withstands high-temp testing, aging, and thermal shock (-75°C to +175°C)
Electrical Performance: Low resistivity, TC of >8W/mK, and minimal outgassing

Industry Standard

Our adhesive sets a new industry standard, delivering a void-free bond line and ensuring exceptional performance.

Highest cohesive energy, stress absorption, and elongation at break.

Unveiling MicroCoat's Breakthrough

Introducing MicroCoat's Breakthrough Product: MCT SD0802-31DA - The Ultimate Conductive Die Attach Adhesive

Precision, performance, and reliability redefined in the industry.

Moisture Resistance and Stability

Unparalleled Moisture Resistance and Stability
Endured over a year at 30°C/85%RH, integrates into MSL1 packaging for stability.

Anti-Bleed Resin Technology

Anti-Bleed Resin Technology for Enhanced Reliability
Cutting-edge resin technology preserves resin system adhesion for wirebond and packaging performance.

Precision Engineering

Precision Engineering for Diverse Applications

Versatile solution for military, medical, optoelectronics, automotive sensors, and more.

Unrivaled Thermal Performance

Unrivaled Thermal Performance
Epoxy ring size: <50um uncured, <75um cured at 150°C.

Withstands extreme conditions, maintaining integrity.

Seamless Application

Seamless Application, Consistent Results
One-part conductive thermosetting adhesive, thixotropic paste consistency.

Easy application through stencil printing or syringe dispense.

Diverse Compatibility

Diverse Compatibility, Zero Compromise
Bonds with various substrates including ceramic, PBGAs, CSPs, LCP, and array packages.

Stable in high-temperature environments.

Engineered for Excellence

Engineered for Excellence
Superior performance in extreme temperature testing, thermal shock resistance (-75°C to +175°C).

Low resistivity, high thermal conductivity (TC of >8W/mK).

Reliability Certified

Reliability Certified
High cohesive energy, stress absorption, and elongation at break.

Thrives at temperatures exceeding 300°C.

MicroCoat's Commitment

MicroCoat's Commitment to Excellence

Revolutionizing Microelectronics Assembly.

A Future of connectivity and reliability with MicroCoats breakthrough.

Contact Information

Contact MicroCoat For more information, technical specifications, and partnership opportunities, contact our dedicated team.

Email: sales@M–coat.com

In Closing

MicroCoat –
Pioneering Connectivity,
Powering the Future

Thank you for your attention.

Any questions?